

SOT741-1

plastic ball grid array package; 376 balls; body 23 x 23 x 1.75 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA376
Package type industry code	BGA376
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	14-1-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	22.8	-	23	23.2	mm
E	package width	22.8	-	23	23.2	mm
A	seated height	[tbd]	-	2.45	2.45	mm
A ₂	package height	1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination	-	-	376	-	



2. Package outline

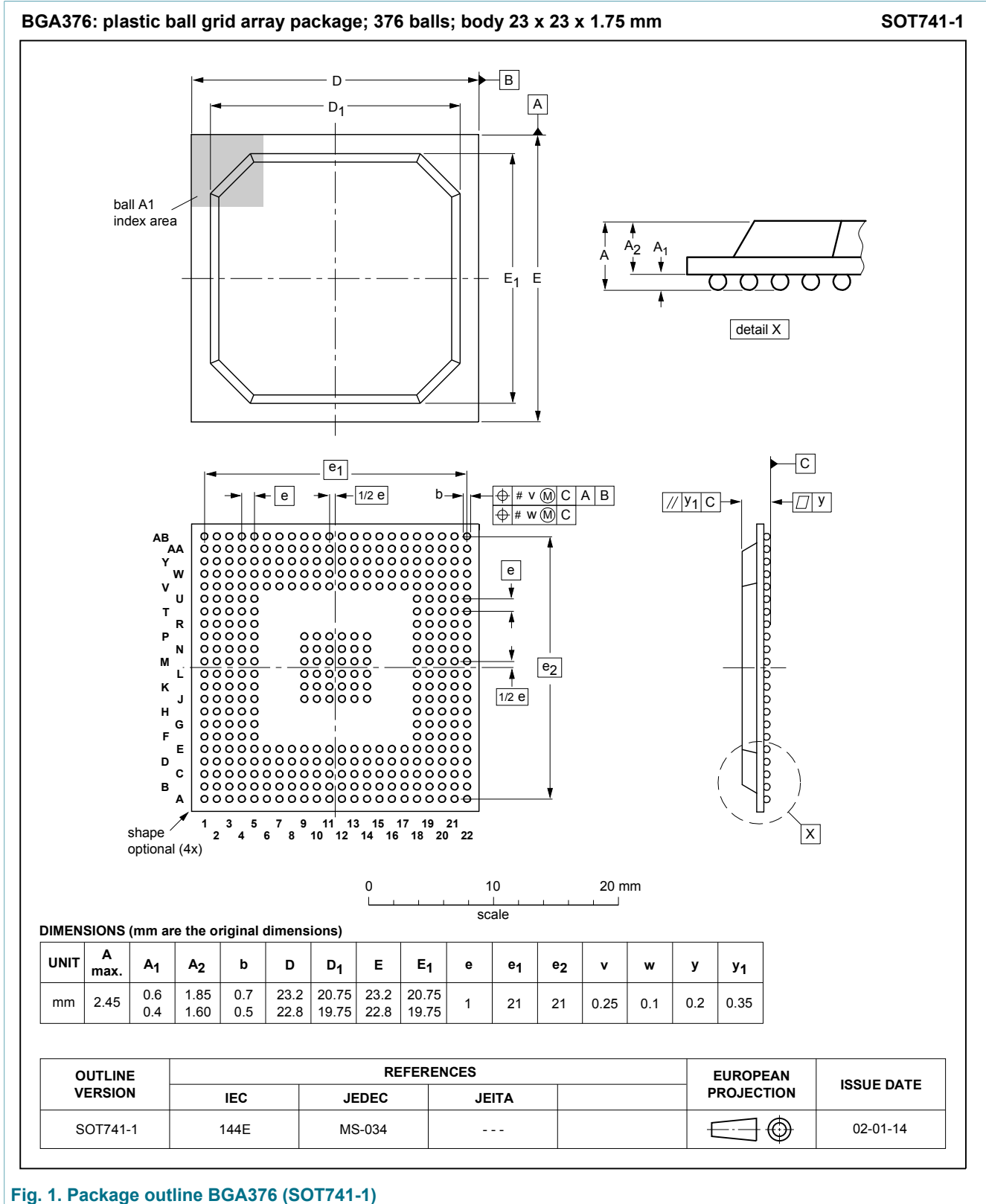


Fig. 1. Package outline BGA376 (SOT741-1)

3. Soldering

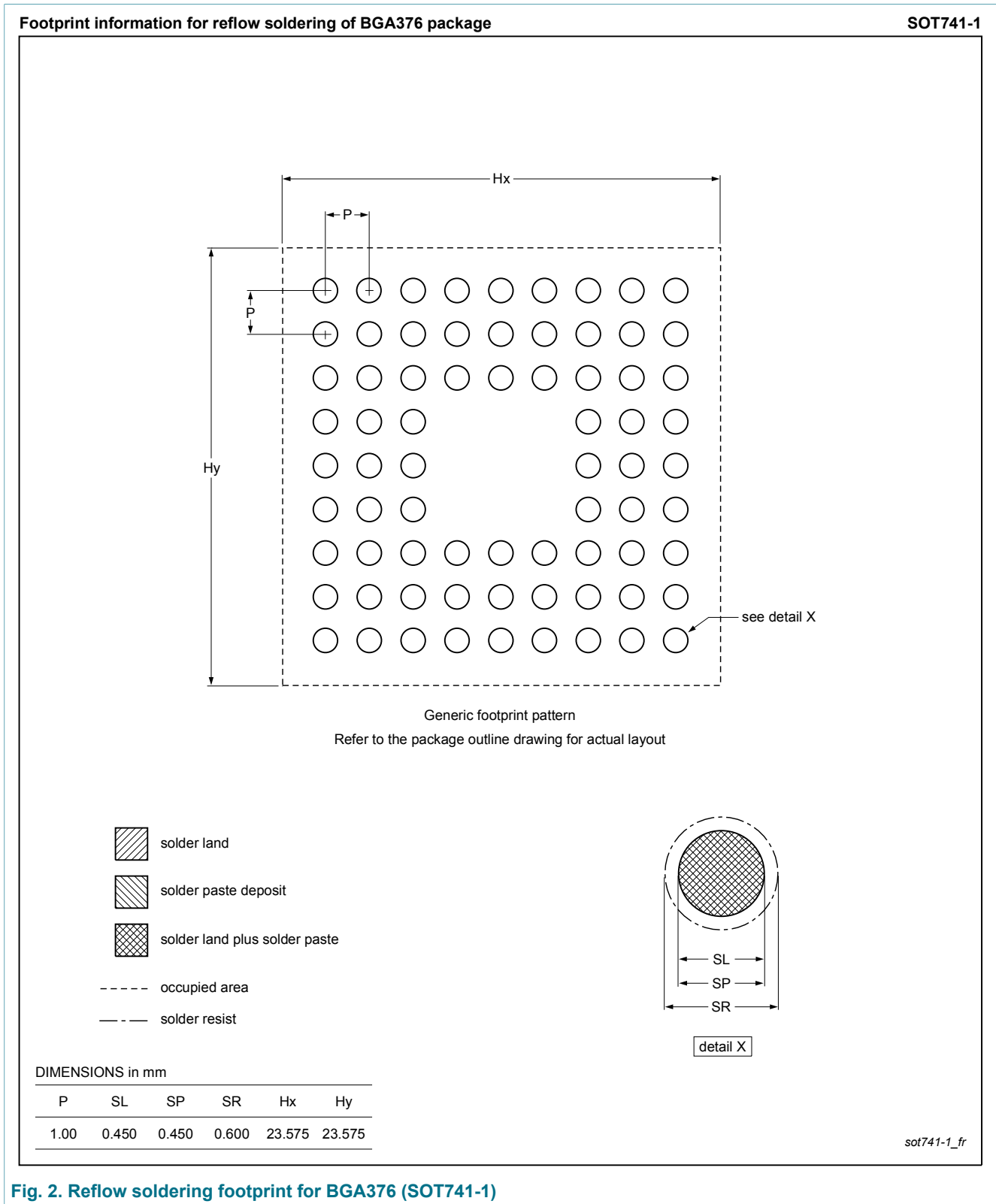


Fig. 2. Reflow soldering footprint for BGA376 (SOT741-1)

4. Legal information

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